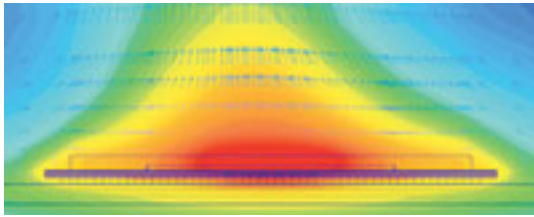


Thermal Testing Standard



Flomerics introduces Version 5 of its web-based Flopack software providing the ability to create Delphi compact models that predict the performance of electronic components under soon-to-be-published thermal testing standards from JEDEC committee JC-15.1. Flopack produces behavioral compact models that can predict the temperature of electronic component packages at critical points such as the junction, case, and board. Version 5.1 also provides a number of new features including a faster, more accurate nonlinear optimizer, support for additional nodes, user access to setup parameters, and the ability to create compact models from non-Flomerics simulation data. Flopack Version 5 provides an advanced nonlinear optimization method that provides more accurate Delphi compact models. The algorithm automatically optimizes the area assigned to each node, eliminating the need for manual nodal partitioning. The optimization method also provides a more flexible objective function that combines flux and junction temperature contributions. Version 5 increases the number of nodes with which the compact model interacts with the environment. In addition to the top inner/outer and bottom inner/outer nodes supported in the past, Version 5 also supports up to two side nodes for all packages and up to four lead nodes for leaded packages.

Flomerics

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